


WE05DMSD
Transient Voltage Suppressor
Features

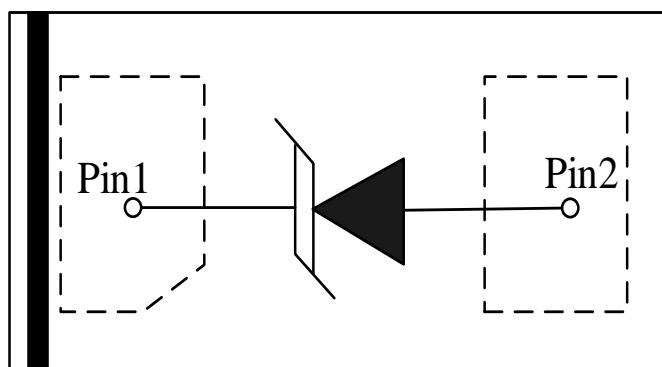
- Small Body Outline Dimensions
- 63 Watts Peak Pulse Power per Line ($t_p=8/20\mu s$)
- ESD Protection of one line
- Low Clamping Voltage
- Working Voltage: 5V
- Low Leakage Current


IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4.5A (8/20 μs)

Mechanical Characteristics Applications

- DFN0603-2L package
- Marking: Marking Code
- Packaging: Tape and Reel
- RoHS Compliant
- Cellular handsets and accessories
- Portable electronics
- Communication systems
- Computers and peripherals

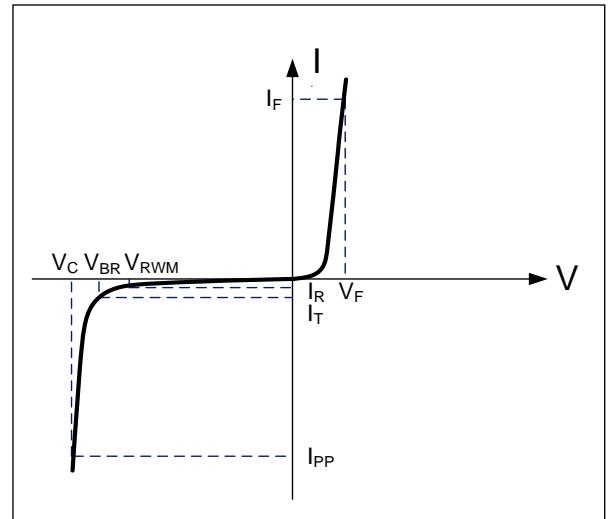
Schematic & PIN Configuration


(TOP VIEW)

Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	63	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	4.5	A
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters ($T=25^\circ C$)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

WE05DMSD						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	6		9	V
Reverse Leakage Current	I_R	$V_{RWM}=5V, T=25^\circ C$			500	nA
Forward Voltage	V_F	$I_F=10mA$	0.5		1.2	V
Clamping Voltage	V_C	$I_{PP}=4.5A, t_p=8/20\mu s$		11	14	V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A$ $t_p = 0.2/100ns$		9.5		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A$ $t_p = 0.2/100ns$		13.6		V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP=0.2/100ns$		0.34		Ω
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		28	40	pF

Note: 1. TLP Setting : $t_p=100ns$, $t_r=0.2ns$, I_{TLP} and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2. Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit"

Typical Characteristics

Figure 1: Peak Pulse Power Vs Pulse Time

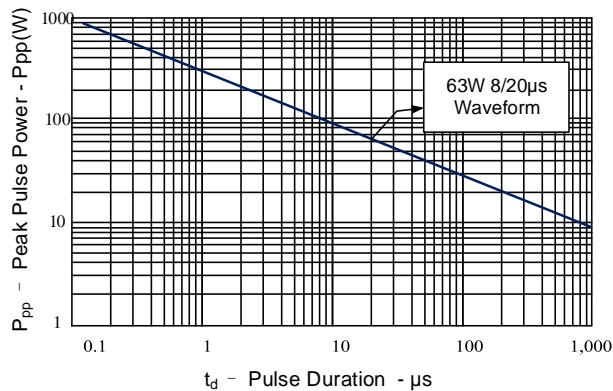


Figure 2: Power Derating Curve

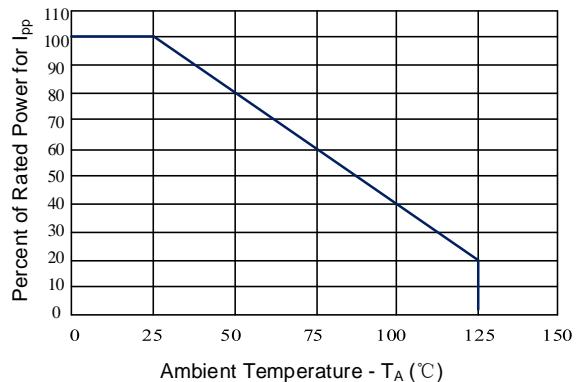


Figure 3: Clamping Voltage vs. Peak Pulse Current

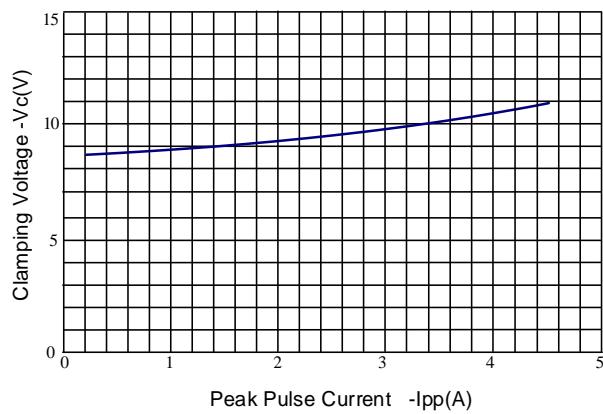


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

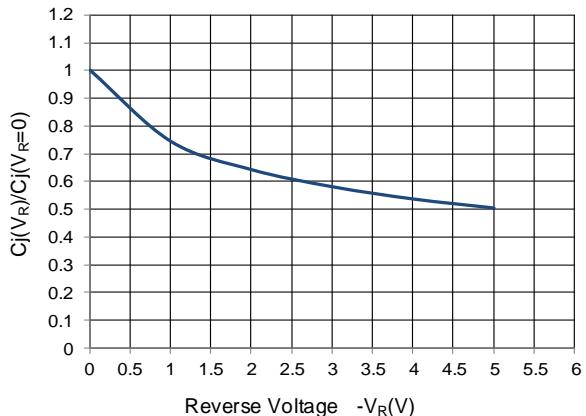


Figure 5: Pulse Waveform

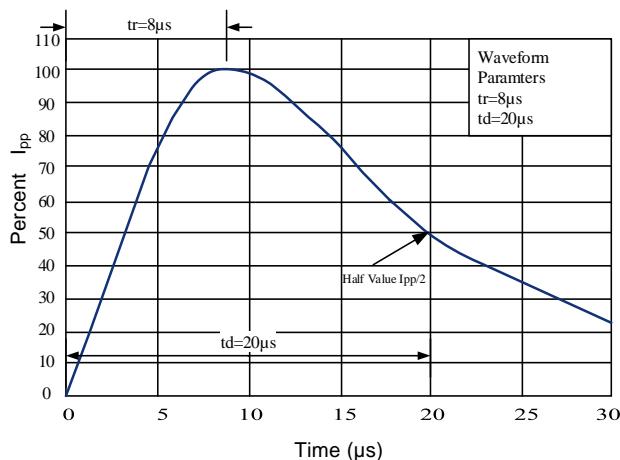
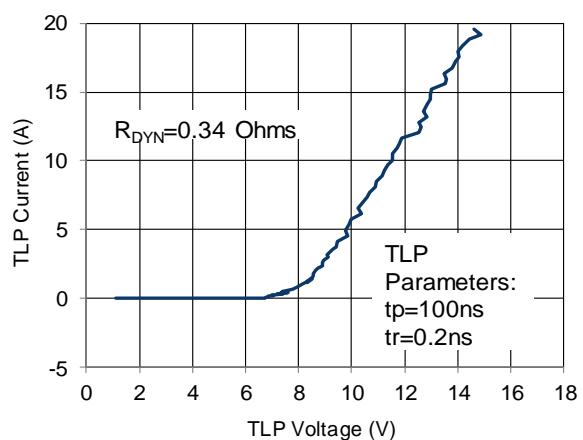
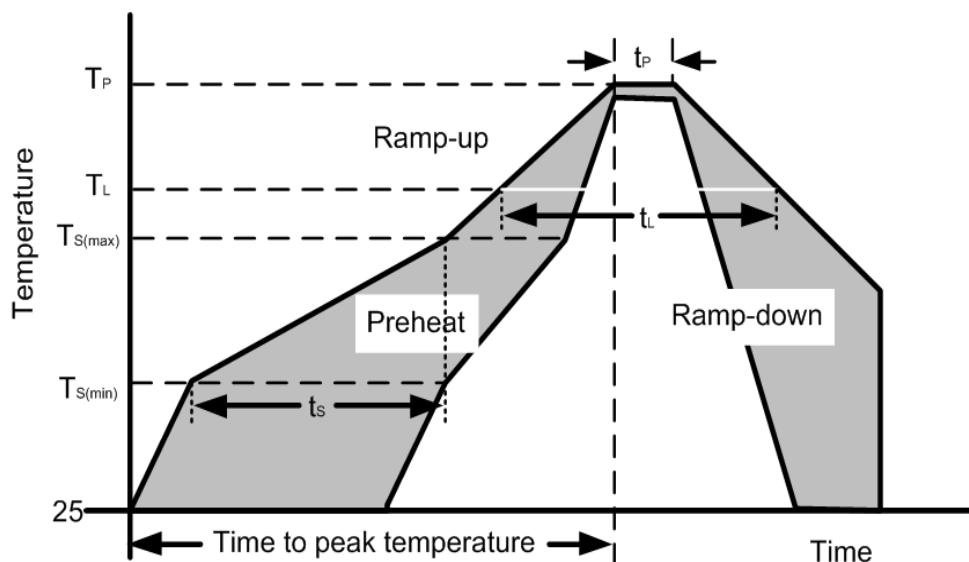


Figure 6: TLP I-V Curve



Soldering Parameters

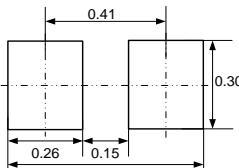
Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
	Peak Temperature (T_P)	260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



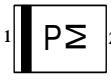
Outline Drawing –DFN0603-2L

PACKAGE OUTLINE						
SYMBOL	MILLIMETERS			Dimension In Inches		
	NOM	MIN	MAX	NOM	MIN	MAX
A	--	0.280	0.320	--	0.011	0.013
A1	--	--	0.050	--	--	0.002
D	0.620	0.570	0.640	0.024	0.022	0.025
E	0.320	0.270	0.340	0.013	0.011	0.013
b	0.180	0.155	0.205	0.007	0.006	0.008
L	0.240	0.200	0.265	0.009	0.008	0.010
h	--	0.050	0.100	--	0.002	0.004
L1	0.040REF			0.002REF		
L2	0.040REF			0.002REF		
e	0.360BSC			0.014BSC		

Land Pattern



Marking Codes

Part Number	Marking Code
WE05DMSD	 P = Specific Device Code M = Month Code

Package Information

Qty: 15k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
 The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
 Users should verify actual device performance in their specific applications.